Claims

The following is a copy of Applicant's claims that identifies language being added with underlining ("___") and language being deleted with strikethrough ("—"), as is applicable:

1. (Currently amended) A flexible circuit, comprising:

a substrate having a first surface on a first side of said substrate, a second surface on a second side of said substrate opposite said first side, and a peripheral edge, said peripheral edge of said substrate forming at least one ~~opening~~ notch that defines an open space;

an electrical conductor bonded to ~~a~~ said first surface of said substrate;

a first cover layer bonded to said first surface of said substrate and to said electrical conductor, said first cover layer extending beyond said peripheral edge of said substrate at said at least one notch so as to extend into said open space; and

a second cover layer bonded to ~~a~~ said second surface of said substrate, said second cover layer also extending beyond said peripheral edge of said substrate at said at least one notch so as to extend into said open space, said second cover layer being bonded ~~and~~ to said first cover layer ~~through said at least one opening~~ at said open space such that said first and second cover layers form an encapsulation region that at least partially encapsulates said substrate~~, wherein said at least one opening is located in an environmentally stressed region~~.

2. (Original) The flexible circuit according to Claim 1, wherein said substrate comprises a polymer.

3. (Original) The flexible circuit according to Claim 1, wherein said electrical conductor comprises a metallic conductor.

4. (Original) The flexible circuit according to Claim 1, wherein said first and second cover layers comprise a polymer.

5-19. (Canceled)

20. (New) The flexible circuit according to Claim 1, wherein said first and second cover layers do not extend beyond said peripheral edge of said substrate along at least a portion of said peripheral edge such that said substrate is only partially encapsulated by said first and second cover layers.

21. (New) The flexible circuit according to Claim 1, wherein said at least one notch is located in an environmentally stressed region of the flexible circuit.

22. (New) The flexible circuit according to Claim 1, wherein said at least one notch comprises an opening that was formed in said substrate and that was cut along a cut line during a singulation process.

23. (New) The flexible circuit according to Claim 1, wherein the flexible circuit is adapted for attachment to a printed circuit board.

24. (New) The flexible circuit according to Claim 1, wherein the flexible circuit is adapted for attachment to a print head.